

IN THE CLAIMS:

Please amend the claims as follows:

Claims 1-4 (Canceled).

Claim 5 (Original): An image pickup device comprising:

a semiconductor substrate having a back surface, serving as a light-incident surface, and a front surface, opposing the back surface and being provided with a charge reading part constituted by a charge coupled device that detects light propagating from the back surface, said semiconductor substrate having a structure such that the thickness of the region at which said charge reading part is disposed is made thinner than the thickness of the remaining region;

a package having a cavity that houses said semiconductor substrate and that is fixed with said semiconductor substrate while the front surface of said semiconductor substrate faces a bottom part of said cavity;

a fiber optic plate having a light outgoing end surface joined to the back surface of said semiconductor substrate while at least a part thereof is housed in said cavity of said package;

a cover covering an upper opening of said cavity of said package, said cover having a guiding opening for inserting at least the part of said fiber optic plate into said cavity; and

electrical wirings for taking out charge signals output from said charge reading part to the exterior of said package, said electrical wirings including substrate-side electrodes disposed on the front surface of said semiconductor substrate, package-side wirings disposed on the bottom surface of said cavity and being electrically connected to said substrate-side electrodes via

bumps disposed on said substrate-side electrodes, and package-side electrodes disposed on an inner wall of said cavity and being electrically connected to said package-side wirings by bonding wires.

Claim 6 (Original): An image pickup device comprising:

a semiconductor substrate having a back surface, serving as a light-incident surface, and a front surface, opposing the back surface and being provided with a charge reading part constituted by a charge coupled device that detects light propagating from the back surface, said semiconductor substrate having a structure such that the thickness of the region at which said charge reading part is disposed is made thinner than the thickness of the remaining region;

a package having a cavity that houses said semiconductor substrate and having one surface whose opening portion is covered by a bottom cover, and the other surface opposing said one surface and whose opening portion is attached with a guide member having a guiding opening, said package being fixed with said semiconductor substrate such that said charge reading part and said bottom cover face each other while said semiconductor substrate is housed;

a fiber optic plate having at least a part housed in said cavity of said package via the guiding opening of said guide member, said fiber optic plate having a light outgoing end surface thereof being joined to the region of the back surface of said semiconductor substrate that is thin in thickness; and

electrical wirings for taking out charge signals output from said charge reading part to the exterior of said package, said electrical wirings including substrate-side electrodes disposed on the front surface of said semiconductor substrate, and package-side electrodes disposed on an

inner wall of said package and being electrically connected to said substrate-side electrodes by bonding wires.

Claim 7 (Canceled)